

<b>Notice of References Cited</b>	Application/Control No. 09/648,750	Applicant(s)/Patent Under Reexamination UCHIBORI, CHIHIRO	
	Examiner Granvill D Lee, Jr	Art Unit 2825	Page 1 of 1

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	C	US-6284656	08-1998	Farrar	438/687
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**NON-PATENT DOCUMENTS**

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	U	Berti et al. "Characterization of a PVD-TiN as the diffusion barrier/adhesion promoter..." Sematech Research pg. 118-119
	V	Moussavi et al. "Comparison of barrier materials and deposition process of copper integration" IEEE IITC 98-295 0-7803-4285-2/98 pg. 295-297.
	W	Baumann et al. "Tin/W double layers as a barrier system for use in Cu metalization" Materials for advanced metallization pg. 128-129
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.